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(12) **United States Design Patent**  
**Lee**

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(54) **HEADPHONE**

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(\*\*) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** ..... **14-01**

(52) **U.S. Cl.** ..... **D14/205**

(58) **Field of Classification Search** ..... D14/188,  
D14/192, 205-206, 223; D29/112, 122;  
2/209; 181/129-130; 381/379-382; 379/430-431  
See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

4,689,822 A \* 8/1987 Houg ..... 381/379  
D300,133 S \* 3/1989 Daidoh et al. .... D14/205

D305,541 S \* 1/1990 Hirose ..... D14/205  
D313,092 S \* 12/1990 Nilsson ..... D29/112  
D328,074 S \* 7/1992 Yamazaki et al. .... D14/205  
5,809,573 A \* 9/1998 Bary ..... 2/209  
D502,938 S \* 3/2005 Tokioka et al. .... D14/205  
D512,983 S \* 12/2005 Tachikawa ..... D14/205  
D525,235 S \* 7/2006 Koizumi ..... D14/205  
D534,155 S \* 12/2006 Obata ..... D14/205  
D534,156 S \* 12/2006 Obata ..... D14/205

\* cited by examiner

*Primary Examiner*—Paula A. Greene

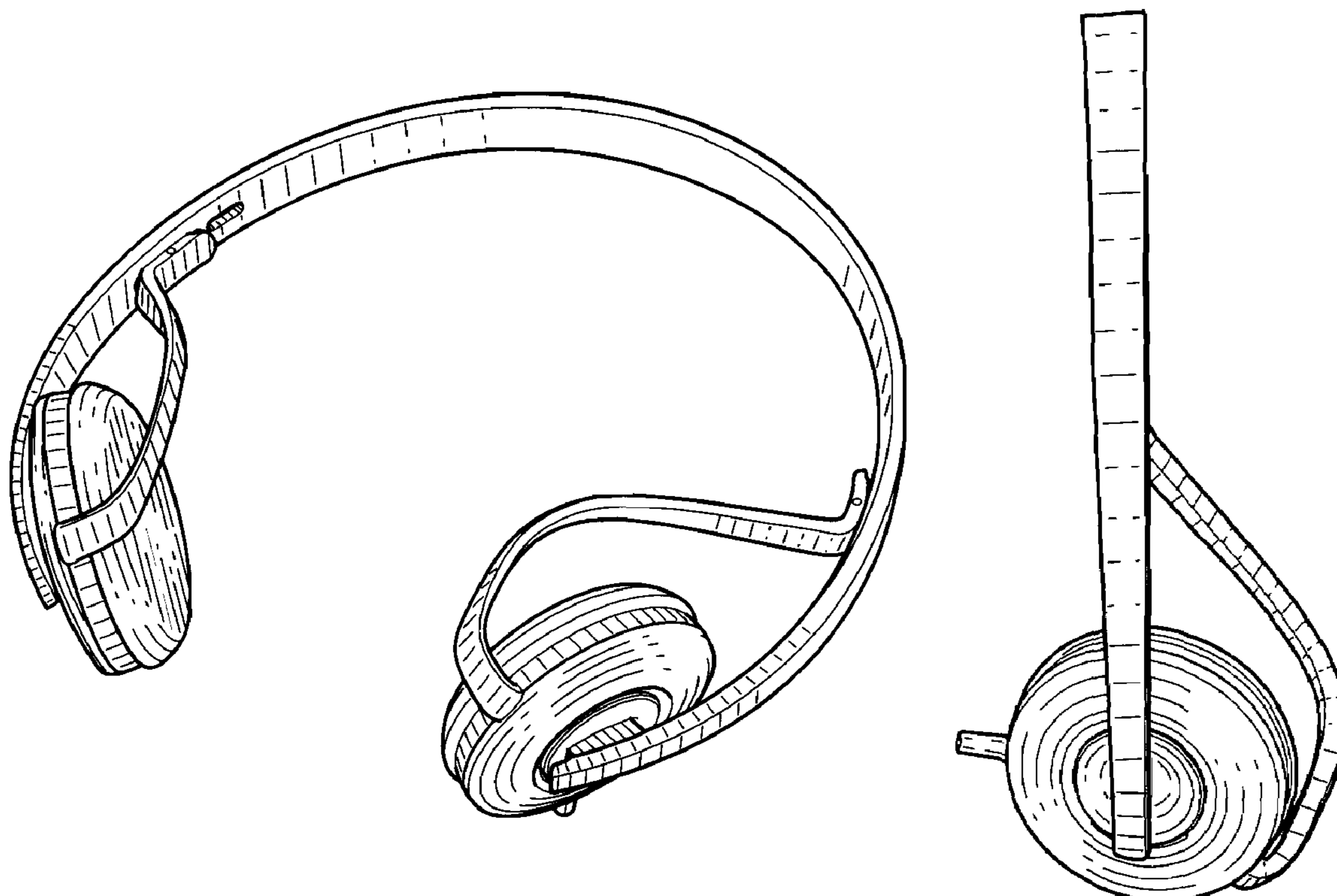
(57) **CLAIM**

The ornamental design for a headphone, as shown.

**DESCRIPTION**

FIG. 1 is a perspective view showing my design;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a rear elevational view thereof;  
FIG. 4 is a right side elevational view thereof;  
FIG. 5 is a left side elevational view thereof;  
FIG. 6 is a top plan view thereof; and,  
FIG. 7 is a bottom plan view thereof.

**1 Claim, 5 Drawing Sheets**



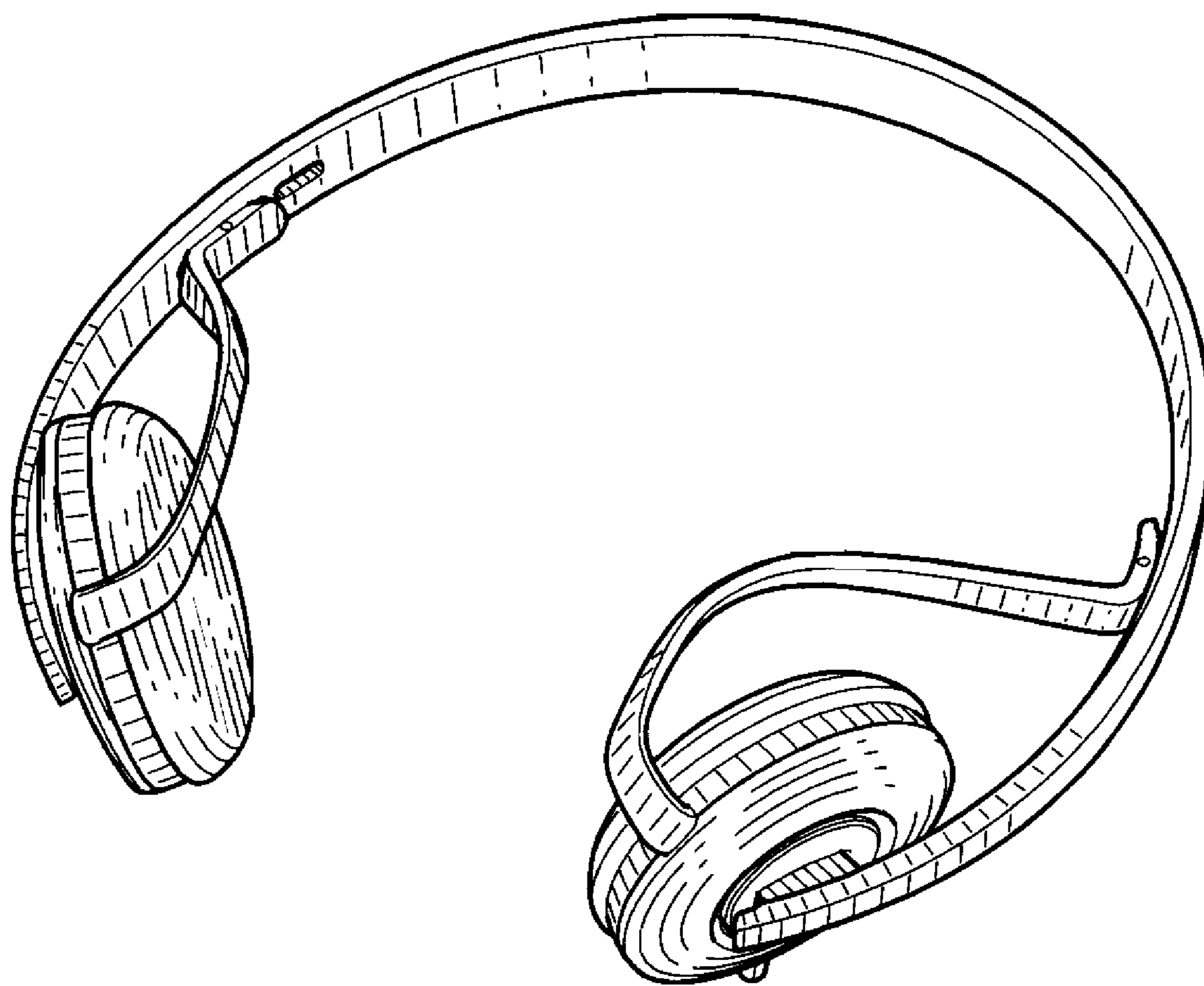


FIG.1



FIG.2



FIG.3

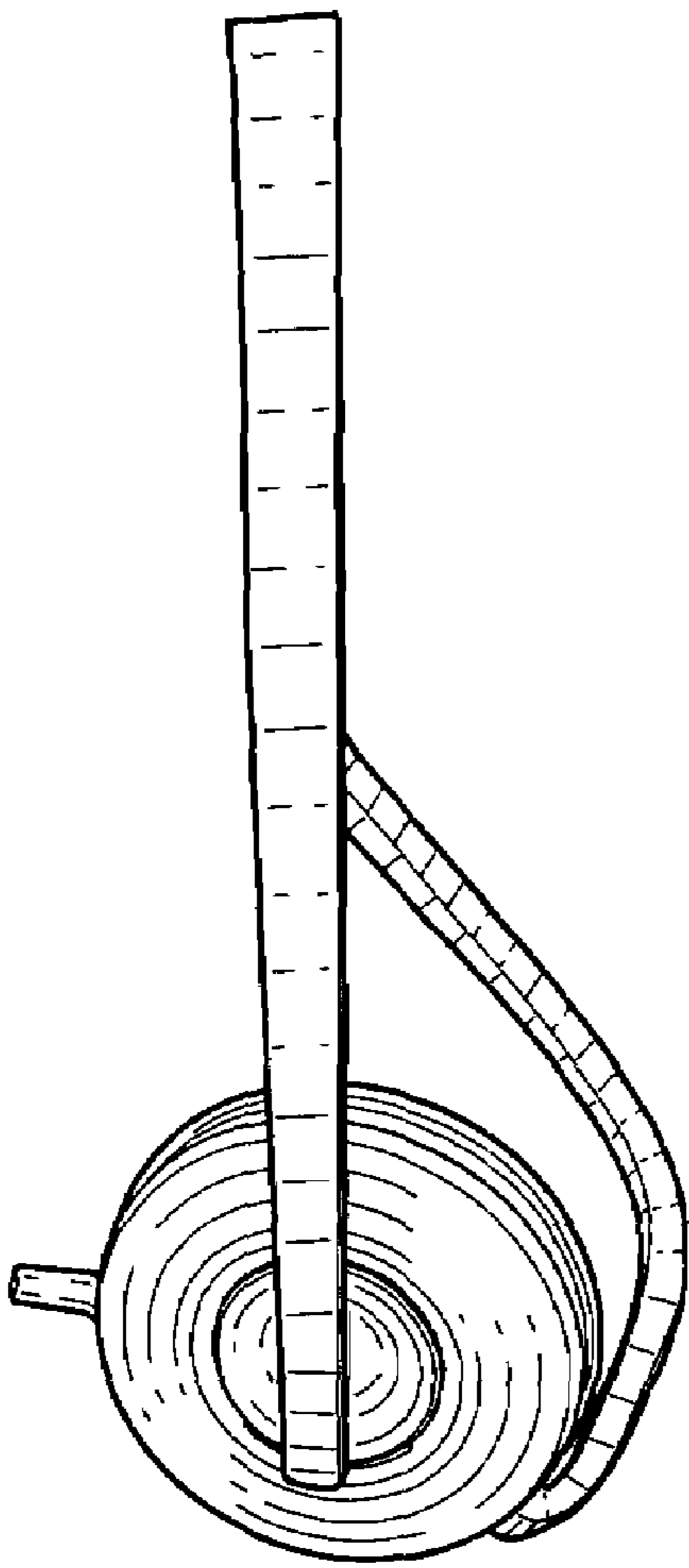


FIG. 4

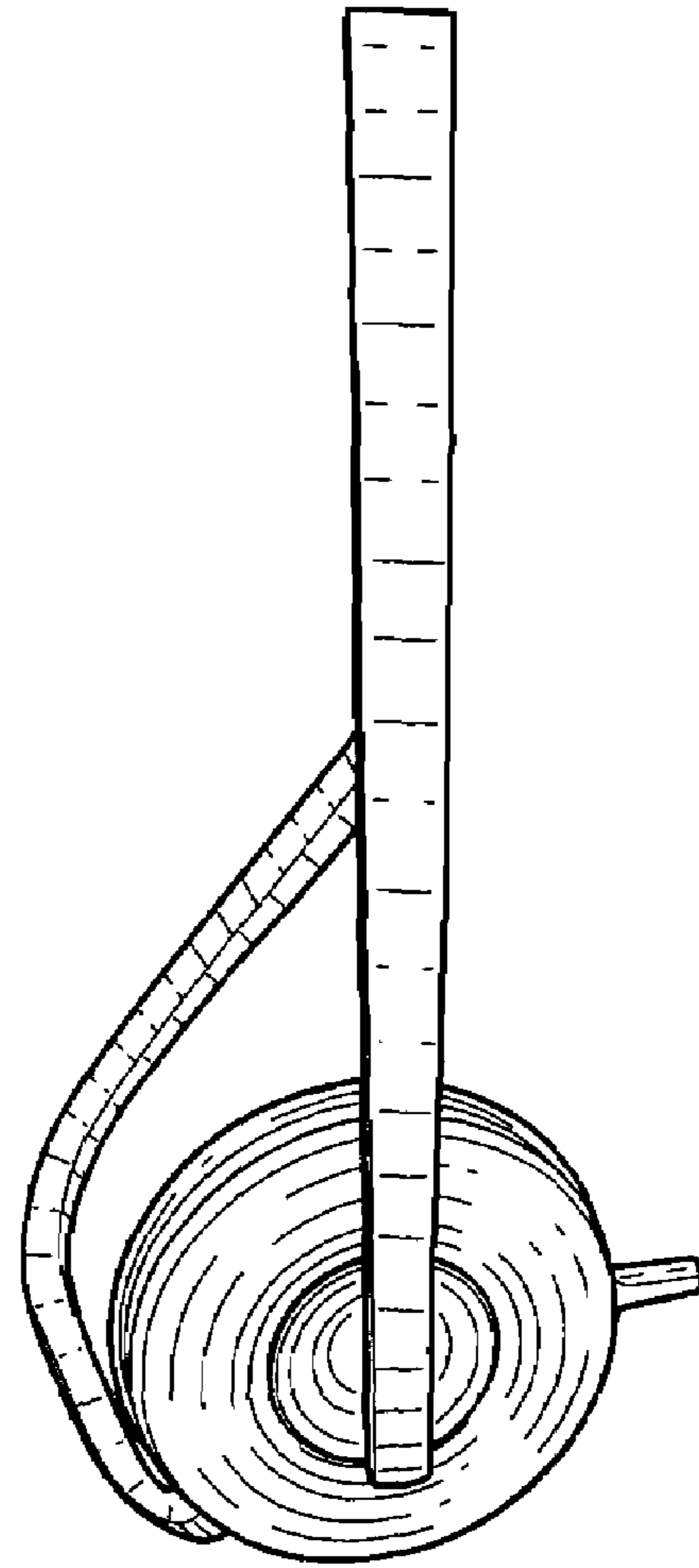


FIG. 5

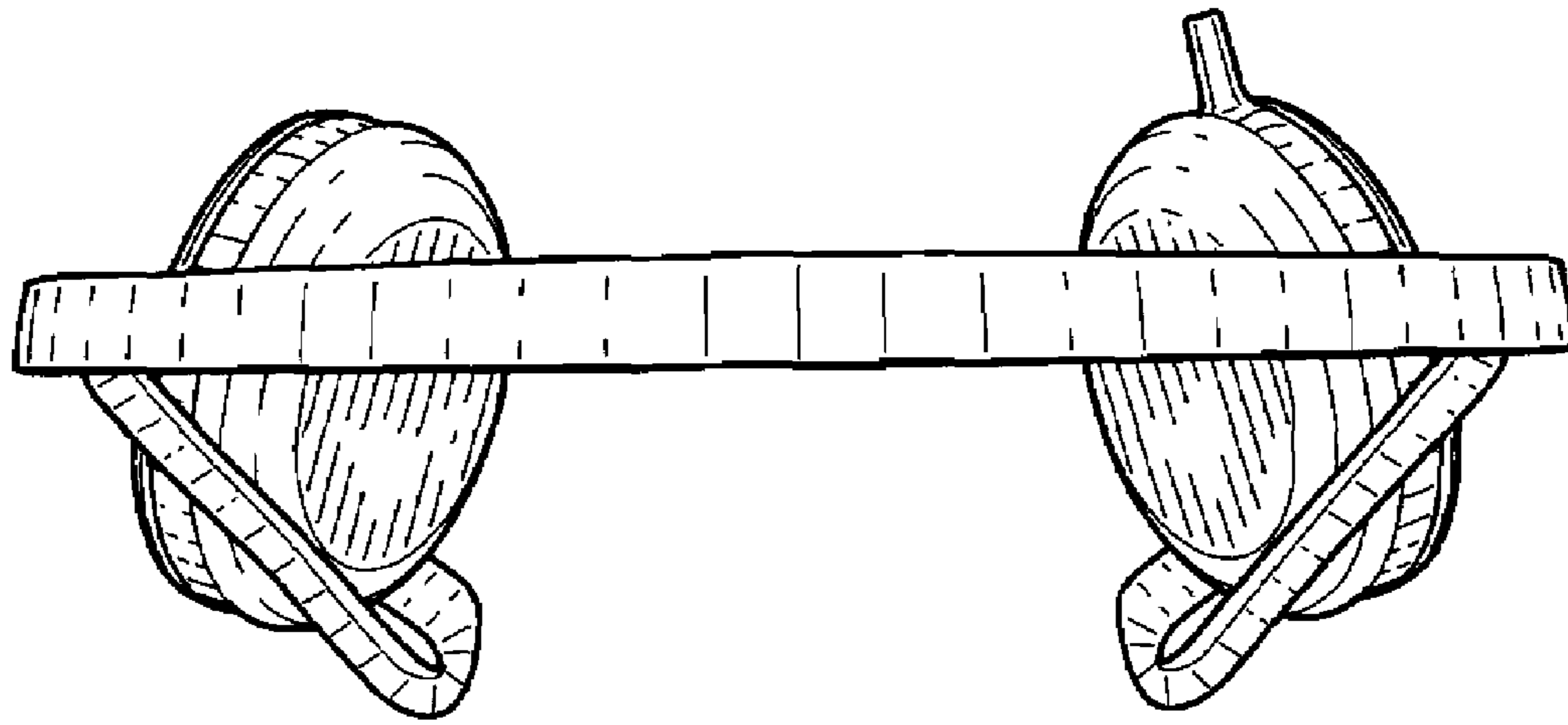


FIG. 6

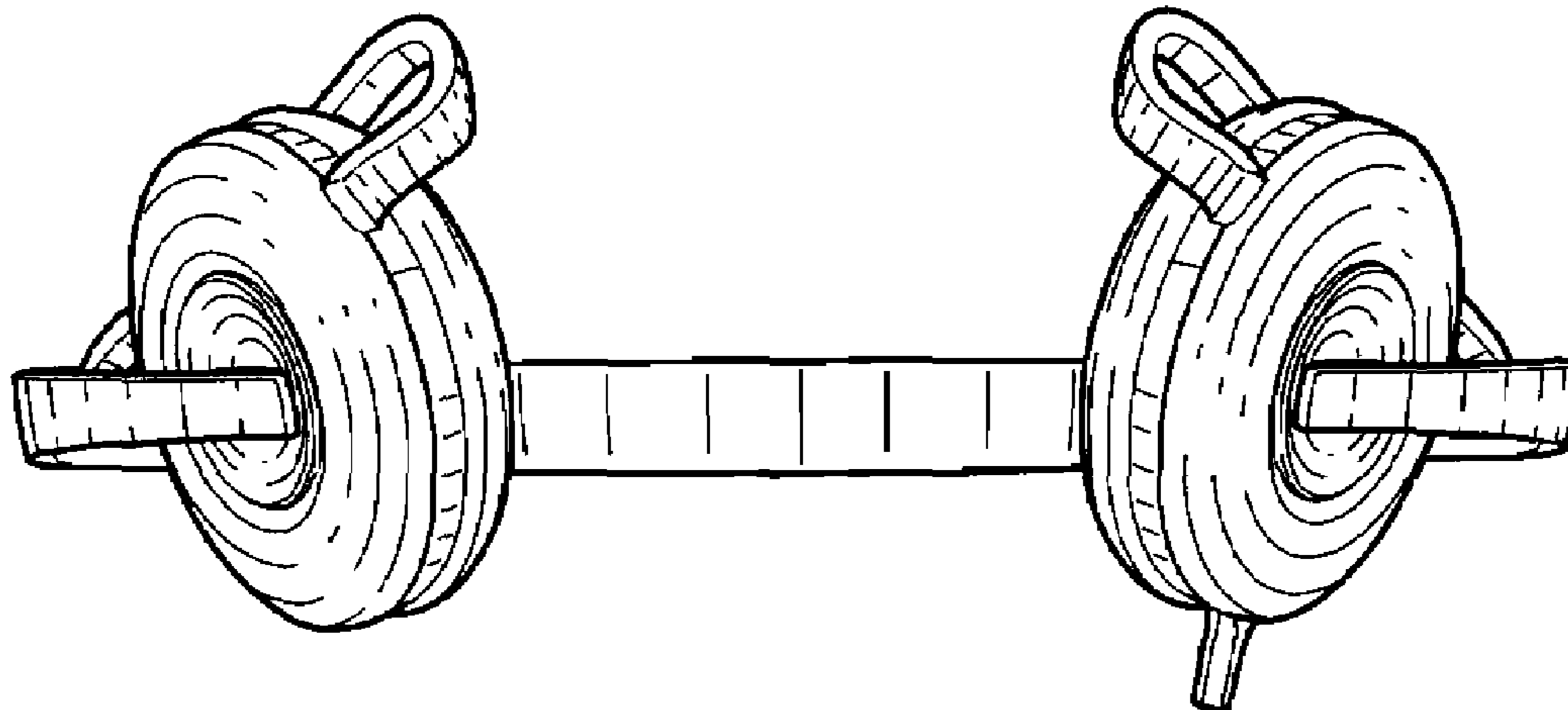


FIG. 7